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What Is Claimed Is:

1. A method of fabricating a liquid crystal display panel, comprising the steps of:

preparing an upper substrate and a lower substrate;

bonding the upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and

eliminating the exposed surfaces of the bonded upper and lower substrates.

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2. The method according to claim 1, wherein the step of cleaning exposed surfaces includes dry-etching.

3. The method according to claim 1, wherein the step of eliminating the exposed surfaces includes wet-etching.

4. The method according to claim 1, further including the steps of:

forming a thin film transistor on the lower substrate;

forming a protective layer on the lower substrate; and

forming a pixel electrode on the protective layer to electrically contact the thin film transistor.

5. The method according to claim 4, wherein the pixel electrode is formed

of a transparent conductive material including indium-tin-oxide (ITO), indium-zinc-oxide (IZO) and indium-tin-zinc-oxide (ITZO).

6. The method according to claim 4, wherein the protective layer is formed of an organic insulating material including an acrylic organic compound, Teflon7, benzocyclobutene (BCB), Cytop7 and perfluorocyclobutane (PFCB).

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7. The method according to claim 4, wherein the step of forming the thin film transistor includes:

forming a gate electrode on the lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and

forming a source electrode and a drain electrode on the active layer.

8. The method according to claim 7, wherein the source electrode and drain electrode contact the gate insulating film.

9. The method according to claim 7, wherein the pixel electrode contacts parallel and inclined surfaces of the drain electrode.

10. A method of fabricating a liquid crystal display panel, comprising the steps of:

bonding an upper substrate to a lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and

removing the exposed surfaces of the bonded upper and lower substrates.

11. The method according to claim 10, wherein the step of cleaning exposed surfaces includes dry-etching.

12. The method according to claim 10, wherein the step of removing the exposed surfaces includes wet-etching.

13. The method according to claim 10, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

14. A method of fabricating a liquid crystal display panel, comprising the steps of:

forming a gate electrode on a lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and

forming a source electrode and a drain electrode on the active layer;

bonding an upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and

removing the exposed surfaces of the bonded upper and lower substrates.

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15. The method according to claim 14, wherein the step of cleaning exposed surfaces includes dry-etching.

16. The method according to claim 14, wherein the step of removing the exposed surfaces includes wet-etching.

17. The method according to claim 14, further including the steps of

forming a protective layer on the lower substrate; and

forming a pixel electrode on the protective layer to electrically contact the drain electrode.

18. The method according to claim 17, wherein the pixel electrode is formed of a transparent conductive material including indium-tin-oxide (ITO), indium-zinc-oxide (IZO) and indium-tin-zinc-oxide (ITZO).

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19. The method according to claim 17, wherein the protective layer is formed of an organic insulating material including an acrylic organic compound, Teflon7, benzocyclobutene (BCB), Cytop7 and perfluorocyclobutane (PFCB).

20. The method according to claim 14, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.